Number of contacts	14, 20, 26, 36, 50, 68
Pitch	1.27 mm
Working current	1 A
Working voltage	240 V ~
Test voltage $U_{r.m.s.}$	750 V (standard) 500 V (light weight)
Contact resistance	≤ 40 mΩ (standard) ≤ 45 mΩ (light weight)
Insulation resistance	≥ 10^3 MΩ
Temperature range during SMC reflow soldering	-55 °C … +105 °C max. 240 °C for 60 s

Terminations

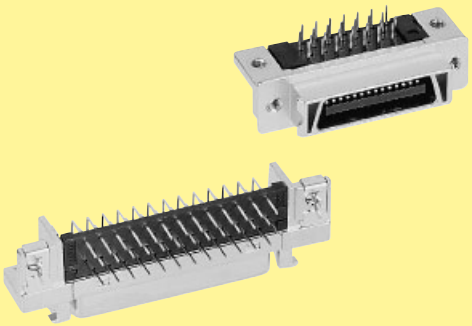
Solder pins	Straight for pcb holes min. Ø 0.74 mm Angled 90° for pcb holes min. Ø 0.74 mm (wave soldering) min. Ø 0.62 mm (light weight)
Insulation displacement	AWG 28 to AWG 30 max. section: 0.089 mm² min. section: 0.050 mm² Insulation Ø min. 0.50 mm Ø max. 0.90 mm

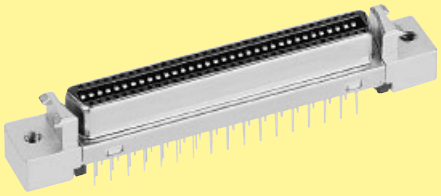
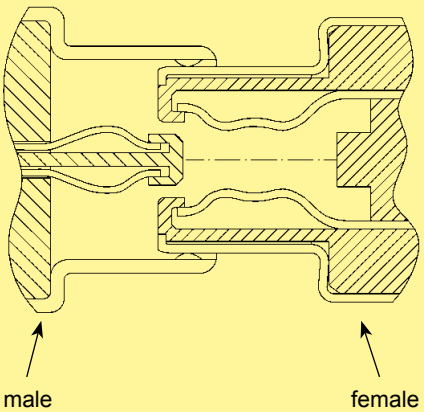
Materials

Moulding	Thermoplastic resin glass-fibre filled UL 94-V0
Contacts	Copper alloy

Contact surface

Contact zone	S4 = 0.76 µm (30 µinch) Au or PdNi equivalent
Metal shell	Die cast zamac or stamped steel, nickel-plated





Bellows
with leaf contact design